Panel Session 7

Board-Level BIST

Moderator: R. Chandramouli, LogicVision
Coordinator: V.K. Agarwal, LogicVision

Panelists:
J. Braden, Stratus
K. Brough, BNI/Nortel
J. Evans, Lockheed Martin
P. McHugh, Army Research Lab
G. Young, Texas Instruments

Abstract:

With the coming of age of BIST technology, its adoption is transcending into various packaging boundaries. Although BIST has been in use for over two decades in mission critical applications (e.g., aerospace), the benefits derived from BIST haven't been fully utilized. Some of the key test issues for board-level products are; the ability to debug and diagnose, field repair, various packaging types (e.g., SMT, BGA) and finally, the ability to manufacture in volume.

Traditional test techniques such as ICT are facing barriers against the above stated issues. The introduction of BIST at the board level can alleviate some of the problems and cut down costs in test time, field repair and enable testing at-speed that guarantees performance. This panel will address the impact of BIST on the issues associated with board-level test. Some of the questions discussed focus on the impact of BIST on board real estate, BIST automation tools, “where should BIST start — at the component level?,” etc.

The panelists comprised of designers and manufacturers of the board level products will discuss these and other questions and debate the merits behind the adoption of BIST as a viable board test technology.